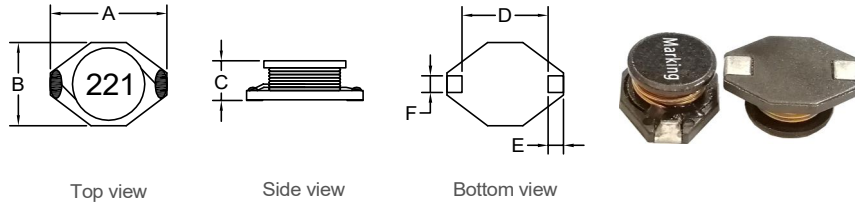


P/N: FASPI-0802T-221K



Outline Dimensions(Unit:mm)



A	B	C	D	E	F
Max	Max	Max	REF	REF	REF
13.2	9.40	3.10	7.62	2.54	2.54

Recommended Soldering Temperature Graph.



Electronical Schematic



Suggested Pad layout



H	2.79 REF
I	2.92 REF
J	7.37 REF

	Standard Profile	Standard Profile
Pre-heating	150~180°C,90s±30s	
Heating	above 220°C,30s-60s	above 240°C,30s Max
Peak temperature	245°C±3°C	260°C,10s
Cycle of reflow	2 times	2 times

Electrical Characteristics(@25°C)

Inductance 100KHz,0.1V	DC Resistor	Isat (A Max)	Irms (A)ΔT≤40°C
220uH±10%	1600mΩ Max	L(0.56A)≥90%*LOA	0.48A

\*\*\*Operating Temperature: -40°C~+125°C  
(Temperature rise included)

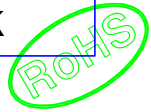
\*\*\*Storage Temperature: -40°C~+125°C

\*\*\*Storage Humidity:RH10%~70%

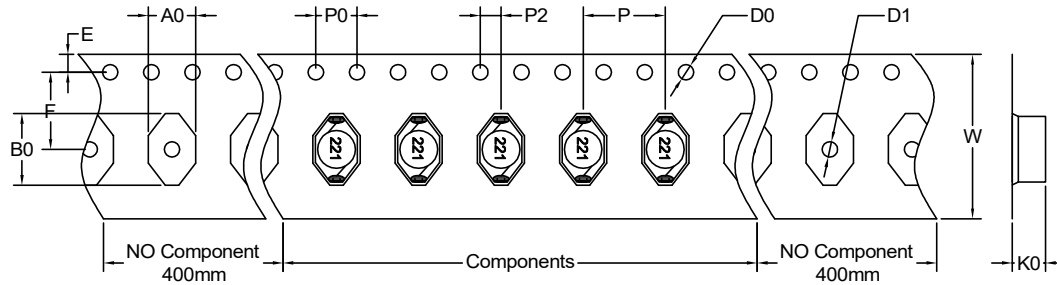
\*\*\*Weight:Approx 0.68g.

REV	DESCRIPTION	APPD	DATE	Tianchang Fuan Electronic Co Ltd www.fuantronics.net TEL: +86-550-7814888 FAX: +86-550-7831133	 Tolerances unless otherwise specified: (.X)±0.50 (.XX)±0.25 Unit of measurement: mm	Make: Qiumei.Liu	<b>DRAWING TITLE</b> SMD NO-SHIELDED POWER INDUCTORS Material Number: A340802XS110	Customer Name:
						Checked: Beson. zhan		Document/Rev: 00
					Approved: Anson. zhan		Specification Sheet: 1 of 4	Date of Recognition: Jan./02/2020

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Packing Specifications(Unit:mm):



A0	10.0	F	11.5
B0	13.5	D0	1.50
P	16.0	D1	1.50
P0	4.00	K0	3.20
P2	2.00	W	24.0
E	1.75		



Quantity:1000pcs/Reel



Quantity: 1000pcs



PE bag



Outer cases: 6000pcs/box  
Insufficient boxes filled with inner boxes or fillers



Inner box  
Quantity: 3000 pcs/box

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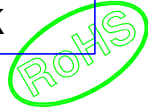
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www.fuantronics.net  
TEL: +86-550-7814888  
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Unit of measurement: mm

Make: Qiumei.Liu  
Checked: Beson. zhan  
Approved: Anson. zhan

**DRAWING TITLE**  
SMD NO-SHIELDED  
POWER INDUCTORS  
Material Number: A340802XS110

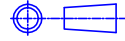
Customer Name:  
Document/Rev: 00  
Specification Sheet: 2 of 4  
Date of Recognition: Jan./02/2020



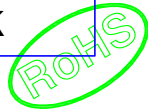
Reliability Testing:

Ltem	Specified value	Test methods
High temperature Storage test Reference documents: MIL-STD-202G Method 108A	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ .	Temperature: $85 \pm 2^\circ\text{C}$ Time: $96 \pm 2$ hours.  Tested not less than 1 hour, not more than 2 hours at room temperature. 
Low temperature Storage test. Referencedocuments: IEC 68-2-1A 6.1 6.2	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ .	Temperature: $25 \pm 2^\circ\text{C}$ Time: $96 \pm 2$ hours.  Tested not less than 1 hour, not more than 2 hours at room temperature. 
Humidity test Reference Documents: MIL-STD-202G Method 103B	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ .	1.Dry oven at a temperature of $40^\circ \pm 5^\circ\text{C}$ for 24 hours. 2.Measurements At the end of this period 3.Exposure:Temperature: $40 \pm 2^\circ\text{C}$ ,Humidity: $93 \pm 3\% \text{RH}$ Time: $96 \pm 2$ hours. 4.Tested while the specimens are still in the chamber. 5.Tested not less than 1 hour, nor more than 2 hours at room temperature. 
Heat endurance of Reflow soldering	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ .	Preheat: $150^\circ\text{C}$ ,60 second. Solder:Sn/Ag/Cu. Solder:Temperature: $260 \pm 5^\circ\text{C}$ . Flux:Rosin flux. Reflow peak time 10 second at $260^\circ\text{C}$ 

Ltem	Specified value	Test methods
Thermal shock test Reference documents: MIL-STD-202G Method 107G	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ . For T:weiges $\leq 28\text{g}$ :15 Min 28g $\geq$ weights $\leq 136\text{g}$ :30 Min	First- $40^\circ\text{C}$ for T time,next+ $125^\circ\text{C}$ Ttime as 1 cycle. Go through 20 cycles. 
Solderability test Reference documents: MIL-STD-202G Method 208H IPC J-STD-002B	Terminals area must have 95% Min. Solder coverage.	Dip pads in flux then dip in solder pot at $245 \pm 5^\circ\text{C}$ for 5 second. Soler:Sn(93.5)Ag(3.5). Flux:Rosin flux.
Vibration test Reference documents: MIL-STD-202G Method 201A	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ .	Apply frequency 10~55Hz. 0.75mm amplitude in each of perpendicular direction for 2 hours.(total 6 hours). 
Drop test Reference documents: MIL-STD-202G Method 203G	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ . For T:weiges $\leq 28\text{g}$ :15 Min 28g $\geq$ weights $\leq 136\text{g}$ :30 Min	Packaged & Drop down from 1m with $981\text{m/s}^2$ (100G)attitude in 1 angle 1 ridges & 2 surfaces orientations.
Terminal strength push test Reference documents: JIS C 5321:1997	Pulling test: DEFINE:A:sectional area of terminal $A \leq 8(\text{Sq M})$ Force $\geq 5\text{N}$ time:30sec $8(\text{Sq M}) < A \leq 20(\text{Sq M})$ Force $\geq 10\text{N}$ time:10sec $20(\text{Sq M}) < A$ force $\geq 20\text{N}$ time:10sec Bending test: Soldering the products on PCB,after the pulling testand bending test, terminal should not pull off	Bend the testing PCB at middle point, the deflection shall be 2mm 

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Ltem	Specified value	Test methods
Resistance to solvent test Reference documents: IEC 68-2-45:1993	No case deformation or change in appearance, or obliteration of marking	To dip parts into IPA solvent for 5±0.5Min, then drying them at room temp for 5 Min, at last, to brushing making 10 times.
Electronic characteristic test of major products	Refer to catalogue of specific products	Refer to catalogue of specific products
Overload test Reference documents:	1. During the test no smoke, no peculiar smell, no fire	Apply twice as rated current for 5 minutes.

Recommended solderability temperature profile:



Use rosin-based flux  
Don't use high acidic flux with halide content exceeding 0.2(wt)% (chlorine conversion value).  
Use lead-free solder, use Sn-3.0Ag-0.5Cu solder  
Standard thickness of solder paste: 0.12-0.15mm

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